

SURFACE MOUNT FAST RECOVERY RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Open Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
250 °C/ 10 seconds at terminals
- ◆ Glass passivated chip junction

Mechanical Data

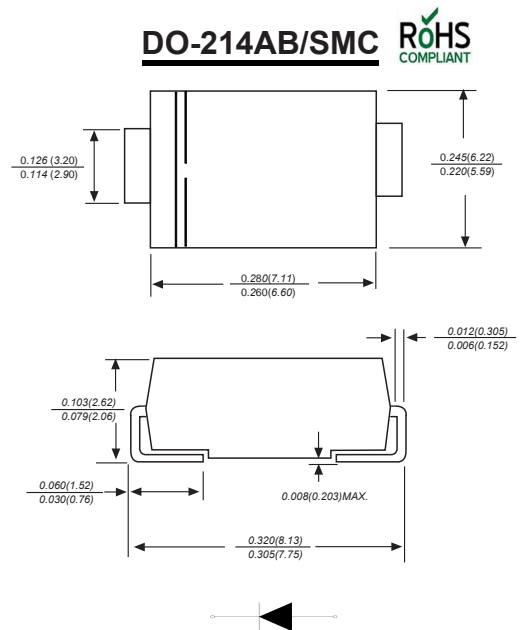
Case : JEDEC DO-214AB/SMC Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.007 ounce, 0.25 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

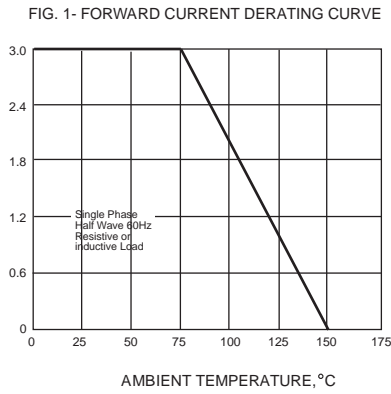
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	RS3A	RS3B	RS3D	RS3G	RS3J	RS3K	RS3M	UNITS
Marking Code									
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=90^{\circ}C$	$I_{(AV)}$	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	100							A
Maximum instantaneous forward voltage at 3.0A	V_F	1.30							V
Maximum DC reverse current $T_A=25^{\circ}C$ at rated DC blocking voltage $T_A=125^{\circ}C$	I_R	5.0 100.0							μA
Maximum reverse recovery time (NOTE 1)	t_{rr}	150				250	500		ns
Typical junction capacitance (NOTE 2)	C_J	60.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	50.0							$^{\circ}C/W$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							$^{\circ}C$

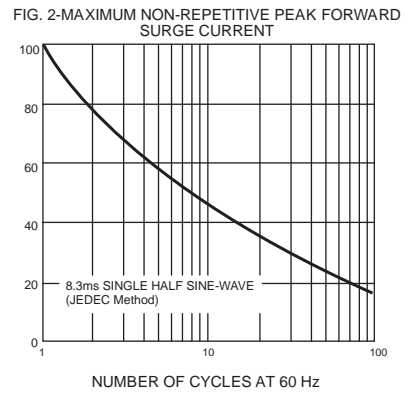
Note: 1. Reverse recovery condition $I_F=0.5A, I_R=1.0A, t_{rr}=0.25A$
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 3. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

Ratings And Characteristic Curves

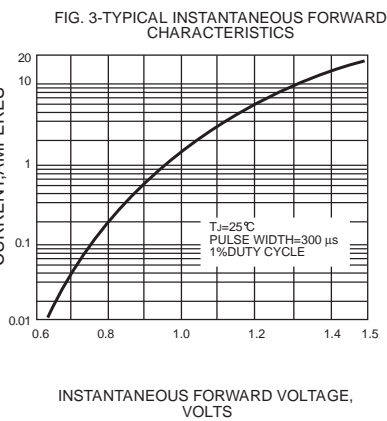
AVERAGE FORWARD RECTIFIED CURRENT,
AMPERES



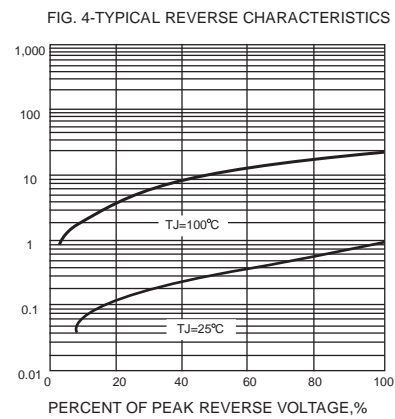
PEAK FORWARD SURGE CURRENT,
AMPERES



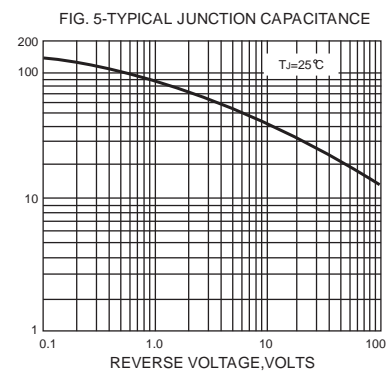
INSTANTANEOUS FORWARD CURRENT,AMPERES



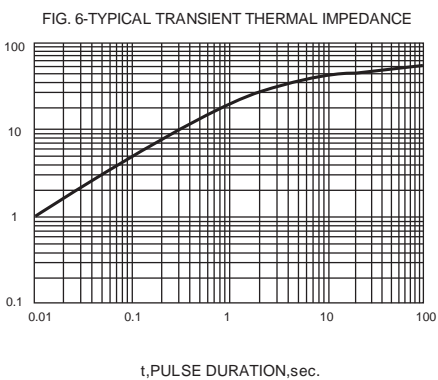
INSTANTANEOUS REVERSE CURRENT,
MICROAMPERES



JUNCTION CAPACITANCE, pF

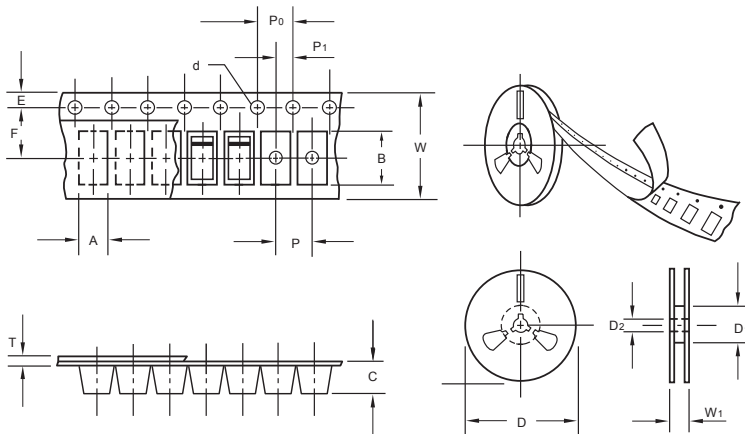


TRANSIENT THERMAL IMPEDANCE,
 $^{\circ}\text{C}/\text{W}$



The curve above is for reference only.

Packing information



unit:mm

Item	Symbol	Tolerance	SMC
Carrier width	A	0.1	6.15
Carrier length	B	0.1	8.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	16.00
Reel width	W ₁	1.0	16.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMC	13"	3,000	4.0	6000	190*190*41	330	365*365*340	42000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	4.3	0.170
B	4.1	0.160
C	7.9	0.311
D	3.8	0.150
E	12	0.472